

FINAL PRODUCT CHANGE NOTIFICATION**PCN:** PCN030061**DATE:** October 7, 2003**Subject:** Rotating pattern on 7C6234*CC devices by 90 degrees**To:****Description of Change:**

Cypress Fab would like to inform our customers who buy wafers from us that the pattern on the 7C6234*CC devices will be rotated 90 degrees and will have a new wafermap.

This will allow the Fab to use the same scanner at local interconnect as is used at other critical layers and will improve overlay at local interconnect. Hence, this will reduce line yield loss and die yield loss due to poor overlay at local interconnect layer.

This change will affect the processes which are dependent on the wafer edge for orientation of the die.

Benefit of Change: Improved availability for customers**Part Numbers Affected:****Affected Parts: 02**

Affected Part	Description
CY62140CV18-3XWI	
CY621451CV18-2XWI	

Customer Part Numbers Affected:**Qualification Status:**

N/A

Sample Status:

Pls see your Sales Representative

Approximate Implementation Date:

WW48

Anticipated Impact:

This change will improve overlay at local interconnect layer and will reduce line yield loss.

FINAL PRODUCT CHANGE NOTIFICATION

Method Of Identification:

N/A

Response Required:

Response not required. This PCN is for information only.

For additional information regarding this change, contact your local sales representative or by E-mail to pcn_adm@cypress.com

Sincerely,

Banjie Bautista
PCN Process Manager

John Quist
Director of Quality Systems